Industry Standard Term Cross Reference

User's Guide

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Cross Reference of TI and National Semiconductor Package Terms

This document is a cross reference of National Semiconductor (NSC) package type names to Texas Instruments (TI) Industry Standard Terms for package types and package families.

NSC to TI Package Types

Legacy NSC Package Term	TI Industry Standard Term
Array LLP	VQFN
CCGA	CPGA
CERDIP	CDIP
CERPACK	CLGA
CPGA	CPGA
CQFP	CFP
CQGP	CFP
CSOP	SOP
EMBEDDED IC	PICOSTAR
EQUAD	QFP
FBGA	NFBGA
FCBGA	FCBGA
FOBGA	BGA
ISOLATED TO220	PFM
LAMINATE CSP	PLGA
LAMINATE TCSP	TLGA
LAMINATE UCSP	ULGA
LBGA	NFBGA
LCC	LCCC
LLP	LQFN
	QFN
	SON
	UQFN
	VQFN
	VSON
	WQFN
	WSON
	X2QFN
	X2SON
LLP COL	UQFN
LLP-MOD	LQFN
LQFP	LQFP
LQFP EXP PAD	HLQFP
LTCC	PLGA

Legacy NSC Package Term	TI Industry Standard Term
MDIP	PDIP
micro SMD	DSBGA
micro SMDxt	DSBGA
MICRO-ARRAY	csBGA
MINI SOIC	VSSOP
MINI SOIC EXP PAD	MSOP-PowerPAD
PBGA	BGA
POS	POS
PQFP	HQFP
	QFP
PSOP	SO PowerPAD
SBGA	BGA
SC-70	SC70
SIDEBRAZE	CDIP SB
SOIC NARROW	SOIC
SOIC WIDE	SOIC
SOT-223	SOT-223
SOT-23	SOT-23
SOT-23 EXP PAD	SOT-23
SSOP	SSOP
TBGA	BGA
TEPBGA	BGA
TFBGA	NFBGA
TO-100	TO-100
TO-220	TO-220
TO-247 SINGLE GAUGE	PFM
TO-252	PFM
TO-263	DDPAK
TO-263	DDPAK/TO-263
TO-263 THIN	PFM
TO-3	TO-3
TO-39	TO
TO-46	TO
TO-5	TO
TO-92	PFM
TO-92	TO-92
TO-99	TO-99
TO-PMOD	PFM
TQFP	TQFP
TQFP EXP PAD	HTQFP
TSOT	SOT
TSSOP	TSSOP
TSSOP EXP PAD	HTSSOP
	MSOP-PowerPAD
	TSSOP
UFBGA	NFBGA

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